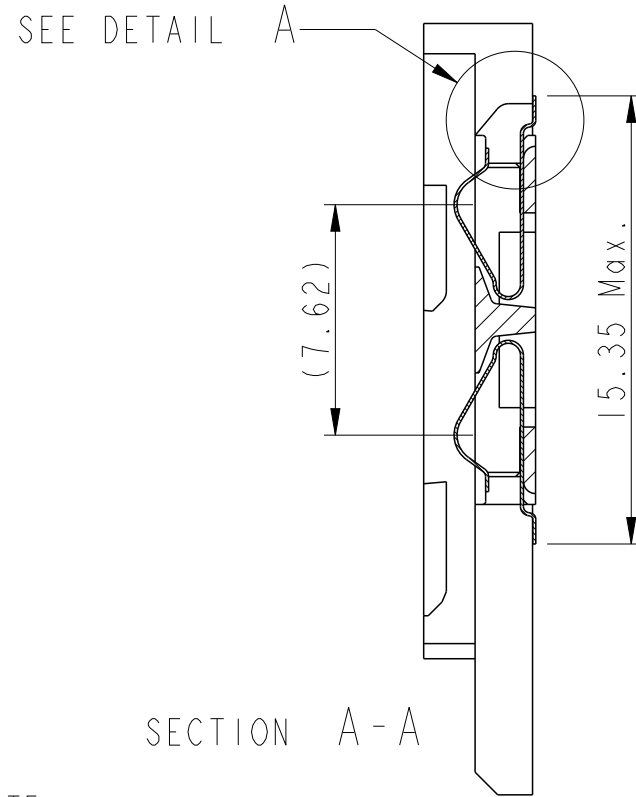
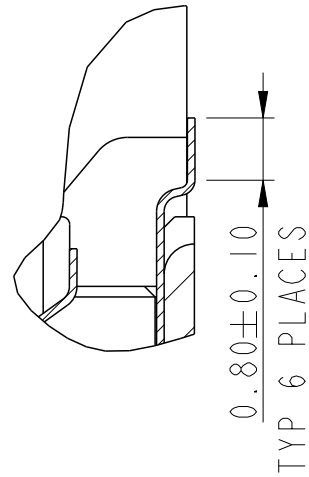


PART NUMBER

7111SI6I5A01LF

DETAIL A
SCALE 10:1



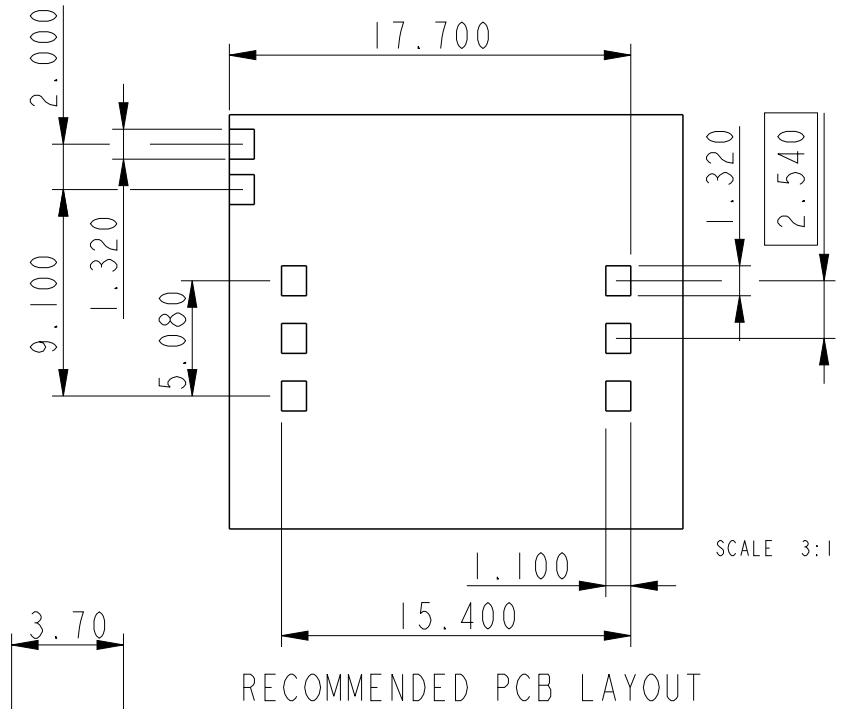
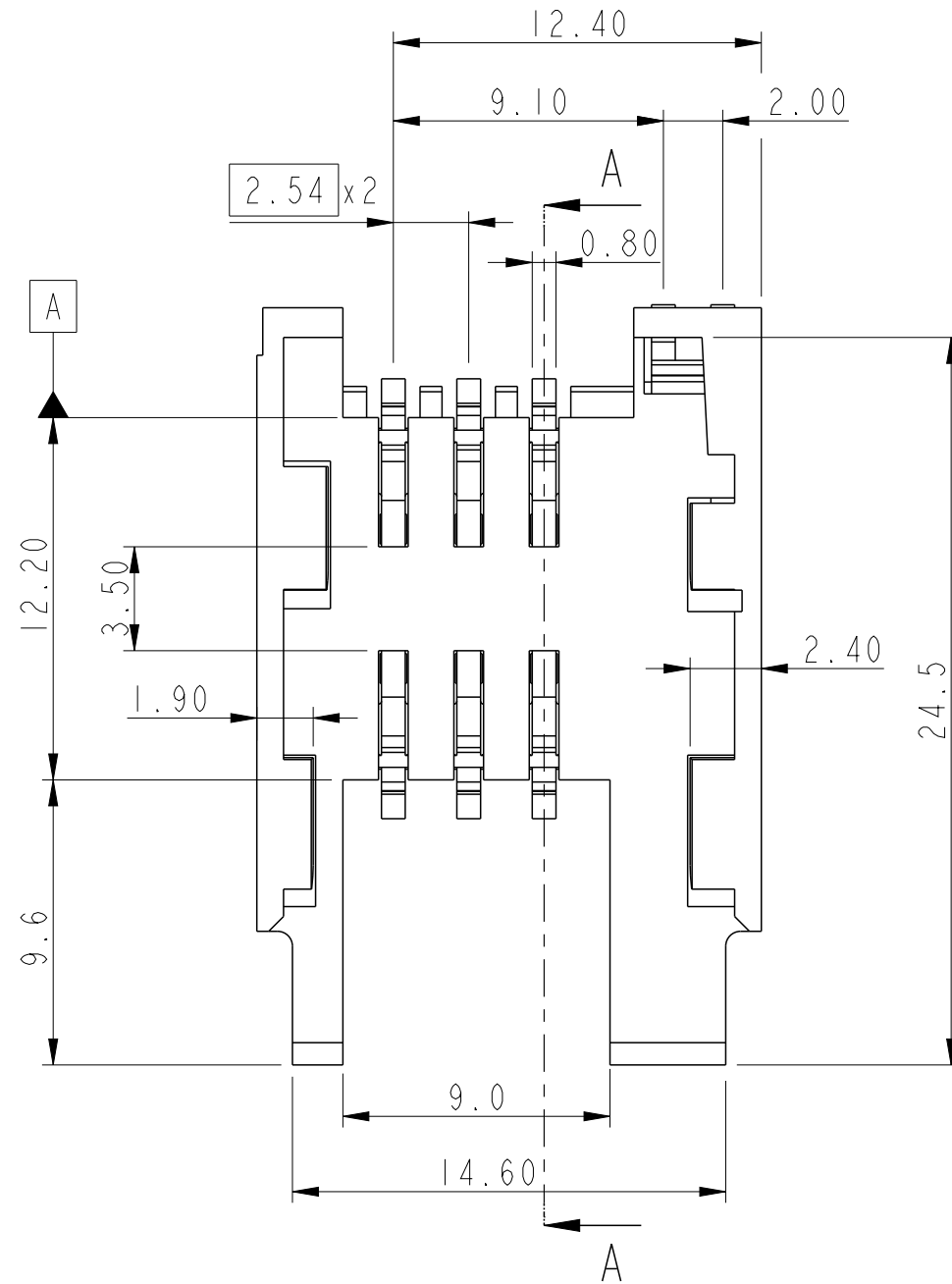
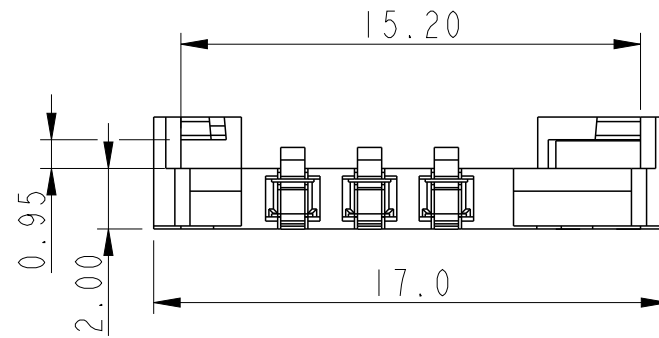
NOTE:

"This product meets European Union Directives and other country regulations as described in GS-47-0004"

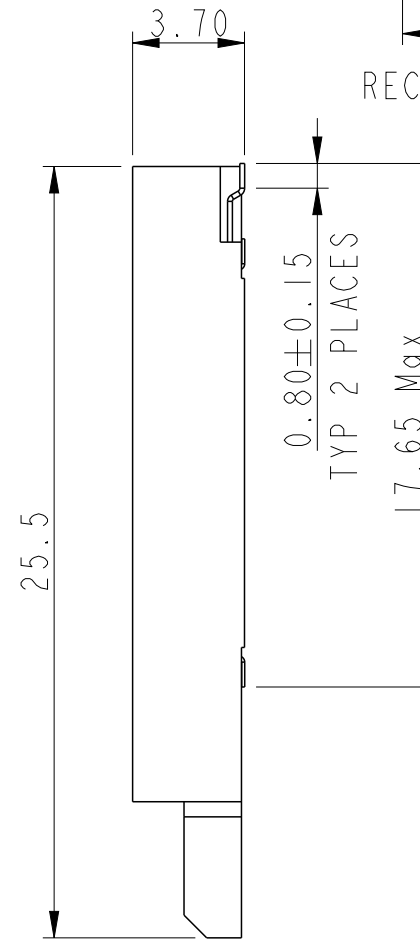
The housing will withstand exposure to 260°C peak temperature for 10seconds in a convection reflow oven.

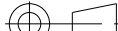

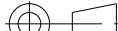

PROCESSING

Ni 2 micrometer
Gold 2.5 µm/Equivalent PdNi over Ni
on contact area
Output : Matte tin 2.5 µm



RECOMMENDED PCB LAYOUT



spec ref		--		dr		P-Mathew Nebu		2011/05/10		projection						size		A3		scale		4:1	
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		P-Mathew Nebu		2017/09/07						ecn no		ELX-I-27477-1							
chr				-		-		product family						MOBILE IO		rel level		Released					
ISO 406 ISO 1101				appr		K-Paul Biju								2017/09/09									
surface		linear		0.X		±0.5		Amphenol FCi		title		SIM CARD CONNECTOR WITH SWITCH		dwg no		VJW53943		rev		G			
				0.XX		±0.25																	
				0.XXX		±0.1																	
ISO 1302		angular		0°		±2°				cat. no.		SEE NOTES		Product - Customer Drw		sheet 1 of 1							